

N-Channel MOSFET

60V 53A TO-252

MFT6N53T252

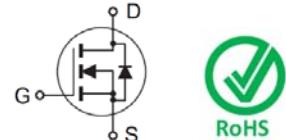
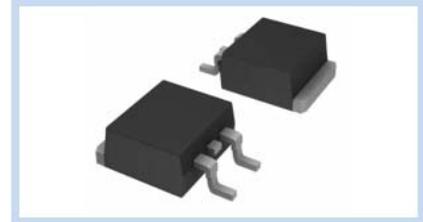
MERITEK

FEATURE

- Simple Drive Requirement
- Low on Resistance
- Fast Switching Characteristics

MECHANICAL DATA

- Case: TO-252 Package
- Terminals: Solderable per MIL-STD-750, Method 2026

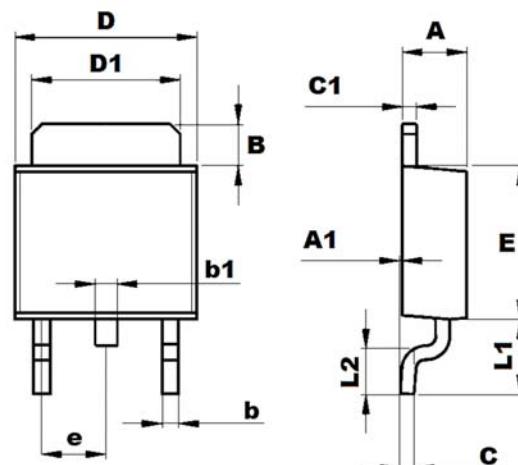


MAXIMUM RATINGS

| Parameter | Symbol | Value | Unit |
|--|-----------------|------------|------|
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current – Continuous | I_D | 53 | A |
| | | 33 | A |
| | | 12 | A |
| | | 9.6 | A |
| Drain Current – Pulsed | I_{DM} | 214 | A |
| Pulsed Body Diode Forward Current | I_S | 10 | A |
| Avalanche Current | I_{AS} | 25 | A |
| Avalanche Energy | E_{AS} | 56 | mJ |
| Power Dissipation | P_D | 50 | W |
| | | 20 | W |
| | | 2.5 | W |
| | | 1.0 | W |
| Thermal Resistance, Junction to Ambient | $R_{\theta JA}$ | 50 | °C/W |
| Thermal Resistance, Junction to Case | $R_{\theta JC}$ | 2.5 | °C/W |
| Operating Junction and Storage Temperature | T_J, T_{STG} | -55 to 150 | °C |

DIMENSIONS

| TO-252 | Min (mm) | Max (mm) |
|--------|-----------|----------|
| A | 2.18 | 2.39 |
| A1 | -- | 0.13 |
| B | 0.89 | 1.27 |
| b | 0.64 | 0.89 |
| C | 0.508 BSC | |
| C1 | 0.46 | 0.89 |
| D | 6.35 | 6.73 |
| D1 | 4.95 | 5.46 |
| E | 5.97 | 6.22 |
| e | 2.29 | -- |
| L1 | 2.74 BSC | |
| L2 | 1.40 | 1.78 |



N-Channel MOSFET

60V 53A TO-252

MFT6N53T252

MERITEK

ELECTRICAL CHARACTERISTICS

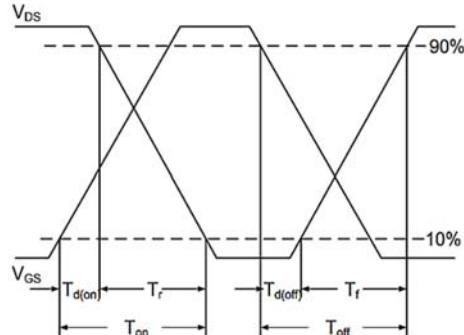
| Off Characteristics | Conditions | Symbol | Min | Typ. | Max | Unit |
|-----------------------------------|--|--------------|-----|------|-----------|-----------|
| Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | BV_{DSS} | 60 | -- | -- | V |
| Drain-Source Leakage Current | $V_{DS}=48V, V_{GS}=0V, T_J=25^\circ C$ | I_{DSS} | -- | -- | 1 | μA |
| Gate-Source Leakage Current | $V_{GS}=\pm 20V, V_{DS}=0V$ | I_{GSS} | -- | -- | ± 100 | nA |
| On Characteristics | Conditions | Symbol | Min | Typ. | Max | Unit |
| Static Drain-Source On-Resistance | $V_{GS}=10V, I_D=12A$ | $R_{DS(ON)}$ | -- | 6 | 8 | $m\Omega$ |
| | $V_{GS}=4.5V, I_D=12A$ | | -- | 9.5 | 13.5 | |
| Gate Threshold Voltage | $V_{GS}=V_{DS}, I_D=250\mu A$ | $V_{GS(th)}$ | 1 | -- | 2.5 | V |
| Forward Transconductance | $V_{DS}=5V, I_D=10A$ | G_F | -- | 21 | -- | S |
| Dynamic Characteristics | Conditions | Symbol | Min | Typ. | Max | Unit |
| Total Gate Charge | $V_{DS}=48V, V_{GS}=10V, I_D=12A$ | Q_g | -- | 37 | -- | nC |
| Gate-Source Charge | | Q_{gs} | -- | 9 | -- | nC |
| Gate-Drain Charge | | Q_{gd} | -- | 8 | -- | nC |
| Turn-On Delay Time | $V_{DS}=30V, V_{GS}=10V, R_G=3\Omega$ $I_D=12A$ | $T_{d(on)}$ | -- | 20 | -- | ns |
| Rise Time | | T_r | -- | 19 | -- | ns |
| Turn-Off Delay Time | | $T_{d(off)}$ | -- | 62 | -- | ns |
| Fall Time | | T_f | -- | 13 | -- | ns |
| Input Capacitance | | C_{iss} | -- | 2333 | -- | pF |
| Output Capacitance | $V_{DS}=30V, V_{GS}=0V, F=1MHz$ | C_{oss} | -- | 338 | -- | pF |
| Reverse Transfer Capacitance | | C_{rss} | -- | 37 | -- | pF |
| Intrinsic Gate Resistance | | R_g | -- | 2 | -- | Ω |
| Drain-Source Body Diode | Conditions | Symbol | Min | Typ. | Max | Unit |
| Reverse Recovery Time | $I_F=10A, dI_F/dt=100A/\mu s$ | t_{rr} | -- | 24 | -- | ns |
| Reverse Recovery Charge | | Q_{rr} | -- | 19 | -- | nC |
| Diode Forward Voltage | $V_{GS}=0V, I_S=10A, T_J=25^\circ C$ | V_{SD} | -- | 0.8 | 1.2 | V |

Note:

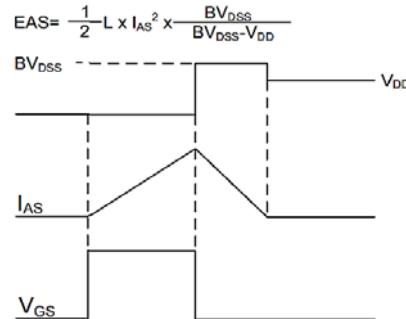
1. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
2. Independent of operating temperature.
3. The Power Dissipation P_D is based on $T_{J(MAX)}=150^\circ C$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used
4. The value of $R_{\Theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2 oz. copper, in a still air environment with $T_A=25^\circ C$. The power Dissipation P_{DSM} is based on $R_{\Theta JA}$ and the maximum allowed junction temperature of $150^\circ C$.

The value in any given application depends on the user's specific board design.

Switching Time Waveform



EAS Waveform



N-Channel MOSFET

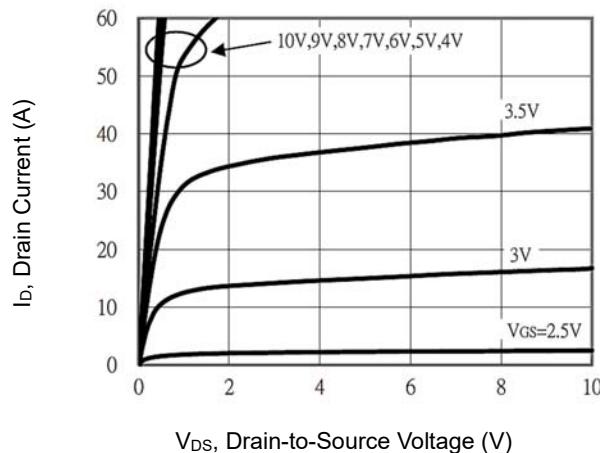
60V 53A TO-252

MFT6N53T252

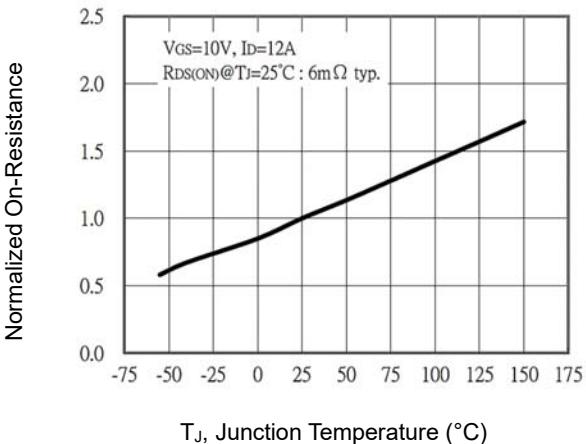
MERITEK

CHARACTERISTICS CURVES

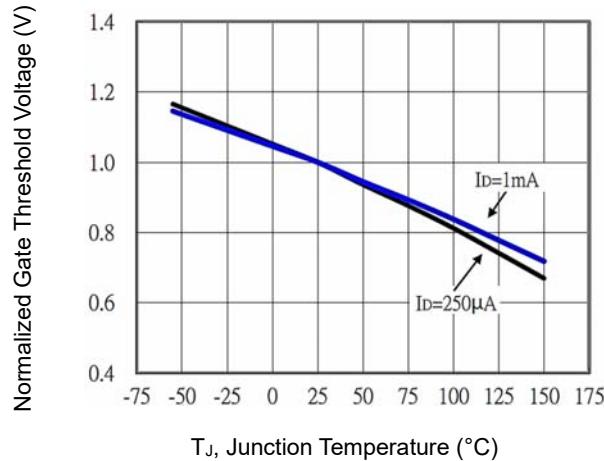
Output Characteristics



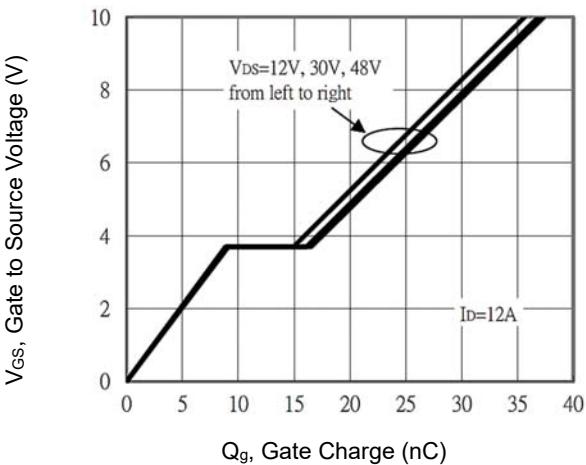
On-Resistance vs. Junction Temperature



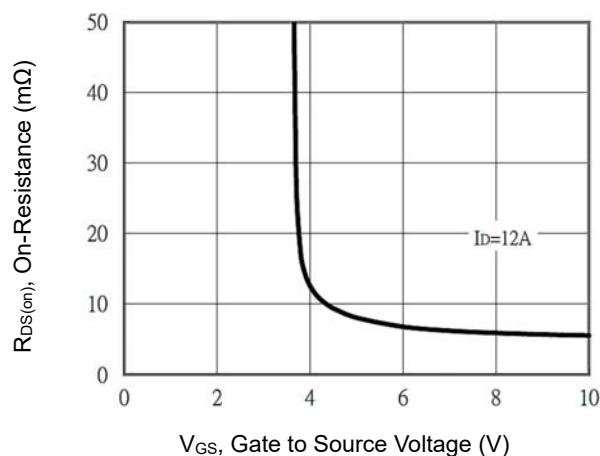
Threshold Voltage vs. Junction Temperature



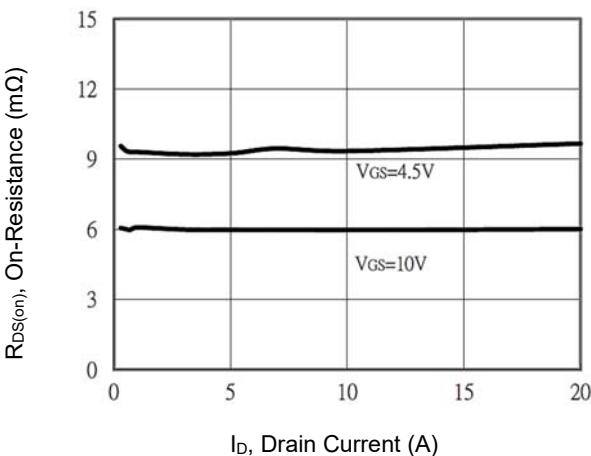
Gate Charge Characteristics



On-Resistance Variation with V_{GS}



On-Resistance vs. Drain Current



N-Channel MOSFET

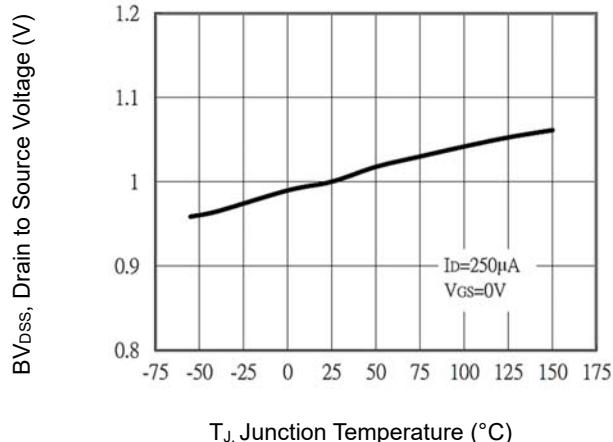
60V 53A TO-252

MFT6N53T252

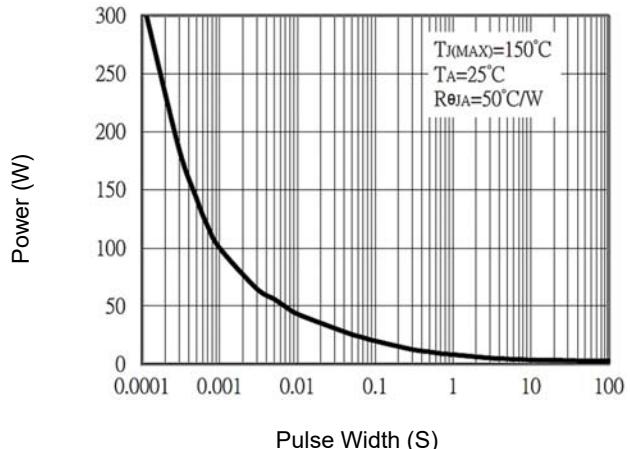
MERITEK

CHARACTERISTICS CURVES

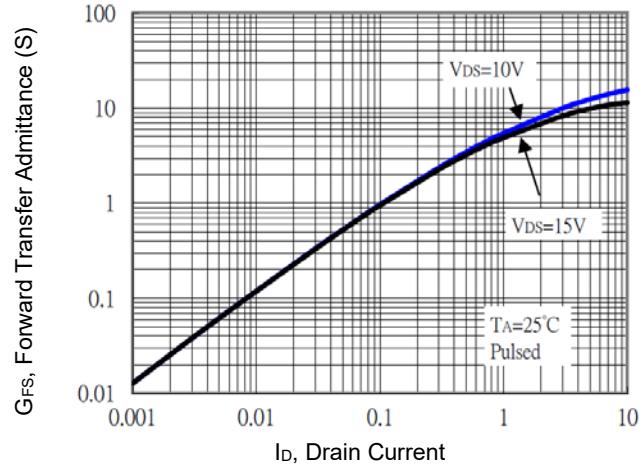
Breakdown Voltage Variation vs. Temperature



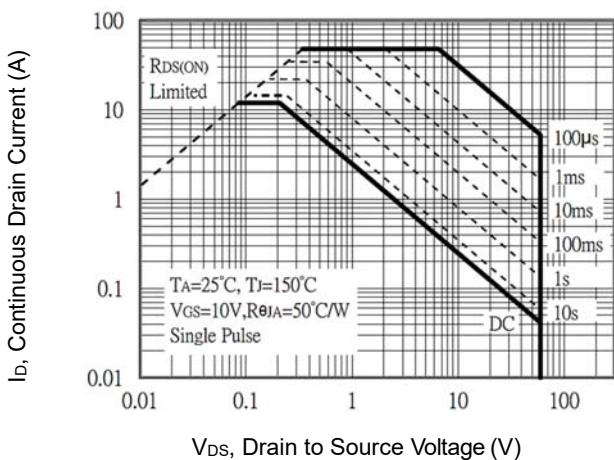
Single Pulse Power Rating, Junction to Case



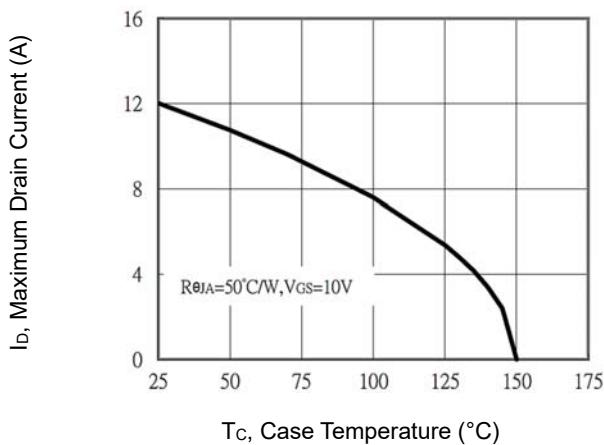
Forward Transfer Admittance vs Drain Current



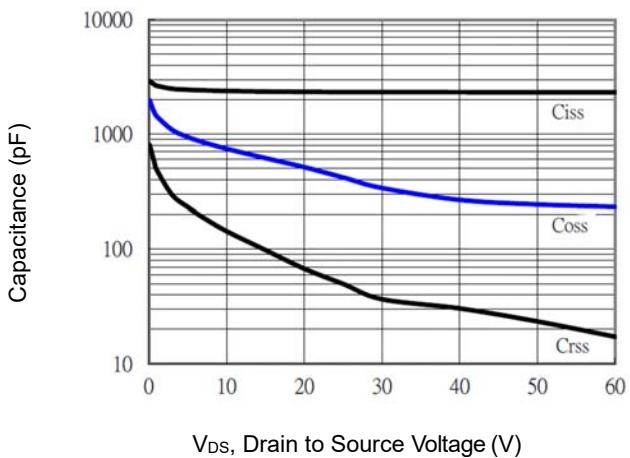
Maximum Safe Operation Area



Maximum Drain Current vs Case Temperature

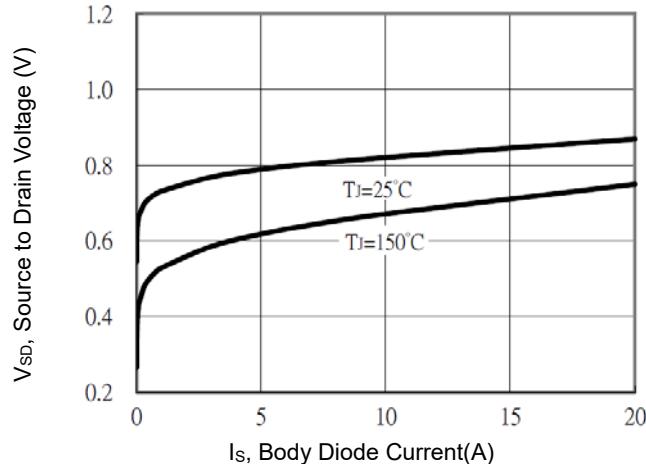


Capacitance vs. Drain-Source Voltage



CHARACTERISTICS CURVES

Body Diode Current vs. Source-Drain Voltage



Normalized Transient Impedance

